Renesas Electronics America Inc - R5F21368SNFA#30 Datasheet

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	I²C, LINbus, SIO, SSU, UART/USART
Peripherals	POR, PWM, Voltage Detect, WDT
Number of I/O	59
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	6K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-20°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f21368snfa-30

1.1.2 Specifications

Tables 1.1 and 1.2 outline Specifications.

Table 1.1 Specifications (1)

Item	Function	Description
CPU	Central processing unit	R8C CPU core • Number of fundamental instructions: 89 • Minimum instruction execution time: 50 ns (CPU clock = 20 MHz, VCC = 2.7 V to 5.5 V) 200 ns (CPU clock = 5 MHz, VCC = 1.8 V to 5.5 V) • Multiplier: 16 bits × 16 bits → 32 bits • Multiply-accumulate instruction: 16 bits × 16 bits + 32 bits → 32 bits • Operating mode: Single-chip mode (address space: 1 Mbyte)
Memory	ROM, RAM, data flash	Refer to **Table 1.3 Product List**.
Voltage detection	Voltage detection circuit	• Power-on reset • Voltage detection with three check points (the detection levels for voltage detection 0 and voltage detection 1 can be selected.)
I/O ports	Programmable I/O ports	• Input only: 1 • CMOS I/O: 59, selectable pull-up resistor • High current drive ports: 59
Clock	Clock generation circuits	• 4 circuits: XIN clock oscillation circuit, XCIN clock oscillation circuit, high-speed on-chip oscillator (with frequency adjustment function), low-speed on-chip oscillator • Oscillation stop detection: XIN clock oscillation stop detection function • Frequency divider circuit: Divided by 1, 2, 4, 8, or 16 can be selected • Low-power mode: Standard operating mode (high-speed clock, low-speed clock, high-speed on-chip oscillator, low-speed on-chip oscillator), wait mode, stop mode
Interrupts		• Number of interrupt vectors: 69 • External interrupt inputs: 9 (INT × 5, key input × 4) • Priority levels: 7
Event link controller (ELC)		• Events output from peripheral functions can be linked to events input to different peripheral functions. (30 sources × 10 types of event link operations) • Events can be handled independently from interrupt requests.
Watchdog timer		• 14 bits × 1 • Selectable reset start function • Selectable low-speed on-chip oscillator for the watchdog timer
DTC (data transfer controller)		• 1 channel • Activation sources: 27 • Transfer modes: 2 (normal mode, repeat mode)
Timer	Timers RJ_0	16 bits × 1: 1 circuit integrated on-chip Timer mode (periodic timer), pulse output mode (output level inverted every period), event counter mode, pulse width measurement mode, pulse period measurement mode
	Timer RB2_0	16 bits × 1: 1 circuit integrated on-chip Timer mode (periodic timer), programmable waveform generation mode (PWM output), programmable one-shot generation mode, programmable wait one-shot generation mode
	Timers RC_0	16 bits (with 4 capture/compare registers) × 1: 1 circuit integrated on-chip Timer mode (input capture function, output compare function), PWM mode (output: 3 pins), PWM2 mode (PWM output: 1 pin)
	Timer RE2	8 bits × 1 Compare match timer mode, real-time clock mode

Table 1.5 Pin Name Information by Pin Number (SSU/I²C, Timer RJ, and Timer RB2)

Port	Pin No.	SSU/I²C						Timer RJ		Timer RB2
		SCL_0	SDA_0	SSI_0	$\overline{SCS\_0}$	SSCK_0	SSO_0	TRJO_0	TRJIO_0	TRBO_0
P0_0	56									
P0_1	55									
P0_2	54									
P0_3	53									
P0_4	52									
P0_5	51									
P0_6	50									
P0_7	49									
P1_0	48									
P1_1	47									
P1_2	46									
P1_3	45									TRBO_0
P1_4	44									
P1_5	43								TRJIO_0	
P1_6	42									
P1_7	41									
P2_0	27									
P2_1	26									
P2_2	25									
P2_3	24									
P2_4	23									
P2_5	22									
P2_6	21									
P2_7	20									
P3_0	1							TRJO_0		
P3_1	29									
P3_2	64								TRJIO_0	
P3_3	19				$\overline{SCS\_0}$					
P3_4	18			SSI_0						
P3_5	17	SCL_0				SSCK_0				
P3_6	28									
P3_7	16		SDA_0				SSO_0			
P4_2	2									
P4_3	4									
P4_4	5									
P4_5	40									
P4_6	9									
P4_7	7									
P5_0	15									
P5_1	14									
P5_2	13									
P5_3	12									
P5_4	11									
P5_6	63									
P5_7	62									
P6_0	61									
P6_1	60									
P6_2	59									
P6_3	58									
P6_4	57									
P6_5	39									
P6_6	38									
P6_7	37									
P8_0	36									
P8_1	35									
P8_2	34									
P8_3	33									
P8_4	32									
P8_5	31									
P8_6	30									

Table 1.6 Pin Name Information by Pin Number (Timer RC, Timer RE2, and Others)

Port	Pin No.	Timer RC						Timer RE2	Others		
		TRCCLK_0	TRCIOA_0	TRCIOB_0	TRCIOC_0	TRCIOD_0	TRCTRG_0	TMRE2O			
P0_0	56		TRCIOA_0				TRCTRG_0		AN7		
P0_1	55		TRCIOA_0				TRCTRG_0		AN6		
P0_2	54		TRCIOA_0				TRCTRG_0		AN5		
P0_3	53			TRCIOB_0					AN4		
P0_4	52			TRCIOB_0				TMRE2O	AN3		
P0_5	51			TRCIOB_0					AN2		
P0_6	50					TRCIOD_0			AN1		
P0_7	49				TRCIOC_0				AN0		
P1_0	48					TRCIOD_0			AN8	$\overline{KI0}$	
P1_1	47		TRCIOA_0				TRCTRG_0		AN9	$\overline{KI1}$	
P1_2	46			TRCIOB_0					AN10	$\overline{KI2}$	
P1_3	45				TRCIOC_0				AN11	$\overline{KI3}$	
P1_4	44	TRCCLK_0									
P1_5	43										
P1_6	42								IVREF1		CH00
P1_7	41								IVCMP1		CH01
P2_0	27			TRCIOB_0							CH16
P2_1	26				TRCIOC_0						CH17
P2_2	25					TRCIOD_0					CH18
P2_3	24										CH19
P2_4	23										CH20
P2_5	22										CH21
P2_6	21										CH22
P2_7	20										CH23
P3_0	1										CH24
P3_1	29										CH10
P3_2	64										CH25
P3_3	19	TRCCLK_0							IVCMP3		
P3_4	18				TRCIOC_0				IVREF3		
P3_5	17					TRCIOD_0					
P3_6	28										CH11
P3_7	16										
P4_2	2								VREF		
P4_3	4								XCIN		
P4_4	5								XCOUT		
P4_5	40								$\overline{ADTRG}$		CH02
P4_6	9								XIN		
P4_7	7								XOUT		
P5_0	15	TRCCLK_0									
P5_1	14		TRCIOA_0				TRCTRG_0				
P5_2	13			TRCIOB_0							
P5_3	12				TRCIOC_0						
P5_4	11					TRCIOD_0					
P5_6	63										CH27
P5_7	62										CH28
P6_0	61							TMRE2O			CH31
P6_1	60										CH32
P6_2	59										CH33
P6_3	58										CH34
P6_4	57										CH35
P6_5	39			TRCIOB_0							CH03
P6_6	38				TRCIOC_0						CH04
P6_7	37					TRCIOD_0					CH05
P8_0	36										CH06
P8_1	35										CH07
P8_2	34										CHxA0
P8_3	33										CHxA1
P8_4	32										CHxB
P8_5	31										CHxC
P8_6	30										CH08

2.1 Data Registers (R0, R1, R2, and R3)

R0 is a 16-bit register for transfer, arithmetic, and logic operations. The same applies to R1 through R3. R0 can be split into high-order (R0H) and low-order (R0L) registers to be used separately as 8-bit data registers. The same applies to R1H and R1L. R2 can be combined with R0 and used as a 32-bit data register (R2R0). Similarly, R3 and R1 can be used as a 32-bit data register.

2.2 Address Registers (A0 and A1)

A0 is a 16-bit register for address register indirect addressing and address register relative addressing. It is also used for transfer, arithmetic, and logic operations. A1 functions in the same manner as A0. A1 can be combined with A0 and used as a 32-bit address register (A1A0).

2.3 Frame Base Register (FB)

FB is a 16-bit register used for FB relative addressing.

2.4 Interrupt Table Register (INTB)

INTB is a 20-bit register that indicates the start address of a relocatable interrupt vector table.

2.5 Program Counter (PC)

PC is a 20-bit register that indicates the address of the next instruction to be executed.

2.6 User Stack Pointer (USP) and Interrupt Stack Pointer (ISP)

The stack pointers (SP), USP and ISP, are each 16 bits wide. The U flag of the FLG register is used to switch between USP and ISP.

2.7 Static Base Register (SB)

SB is a 16-bit register used for SB relative addressing.

2.8 Flag Register (FLG)

FLG is an 11-bit register that indicates the CPU state.

2.8.1 Carry Flag (C)

The C flag retains carry, borrow, or shift-out bits that have been generated in the arithmetic and logic unit.

2.8.2 Debug Flag (D)

The D flag is for debugging only. It must only be set to 0.

2.8.3 Zero Flag (Z)

The Z flag is set to 1 when an arithmetic operation results in 0. Otherwise it is set to 0.

2.8.4 Sign Flag (S)

The S flag is set to 1 when an arithmetic operation results in a negative value. Otherwise it is set to 0.

2.8.5 Register Bank Select Flag (B)

Register bank 0 is selected when the B flag is 0. Register bank 1 is selected when this flag is 1.

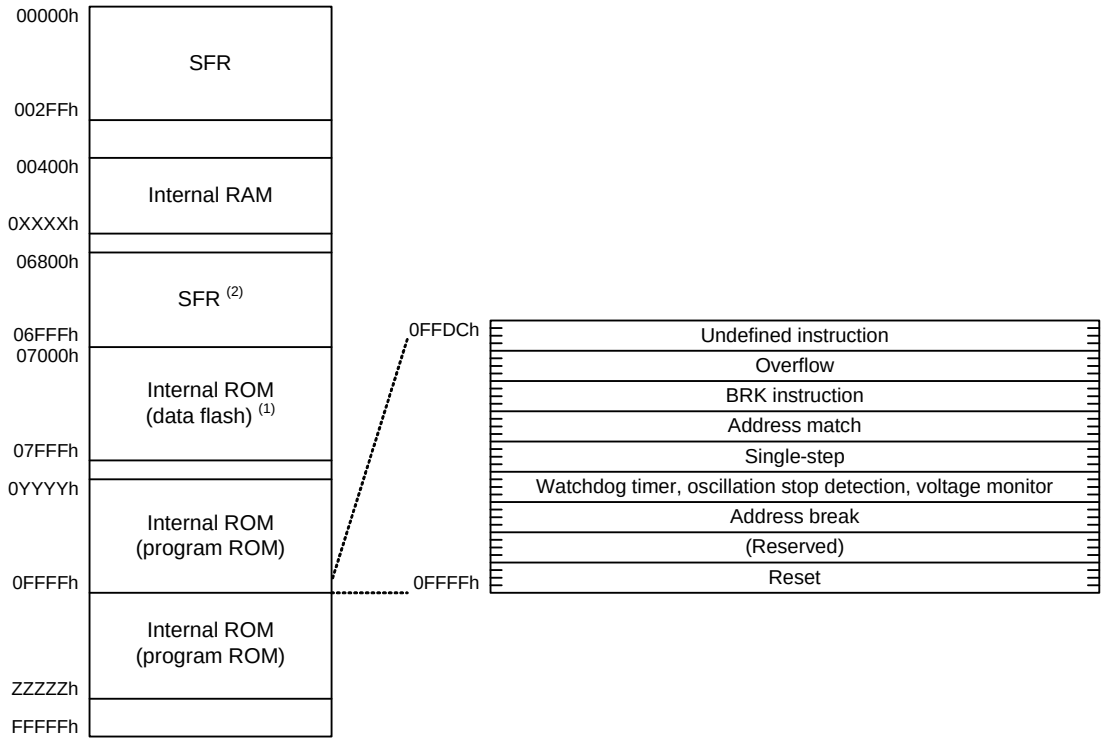
2.8.6 Overflow Flag (O)

The O flag is set to 1 when an operation results in an overflow. Otherwise it is set to 0.

3. Address Space

3.1 Memory Map

Figure 3.1 shows the Memory Map. The R8C/36T-A Group has a 1-Mbyte address space from addresses 00000h to FFFFFh. Up to 32 Kbytes of the internal ROM (program ROM) is allocated at lower addresses, beginning with address 0FFFFh. The area in excess of 32 Kbytes is allocated at higher addresses, beginning with address 10000h. For example, a 64-Kbyte internal ROM is allocated at addresses 08000h to 17FFFh.
The fixed interrupt vector table is allocated at addresses 0FFDCh to 0FFFFh. The start address of each interrupt routine is stored here.
The internal ROM (data flash) is allocated at addresses 07000h to 07FFFh.
The internal RAM is allocated at higher addresses, beginning with address 00400h. For example, a 6-Kbyte internal RAM is allocated at addresses 00400h to 01BFFh. The internal RAM is used not only for data storage but also as a stack area when a subroutine is called or when an interrupt request is acknowledged.
Special function registers (SFRs) are allocated at addresses 00000h to 02FFFh and addresses 06800h to 06FFFh. Peripheral function control registers are allocated here. All unallocated locations within the SFRs are reserved and cannot be accessed by users.



Notes:
1. Data flash indicates block A (1 Kbyte), block B (1 Kbyte), block C (1 Kbyte), and block D (1 Kbyte).
2. Addresses 06800h to 06FFFh are used for the ELC, DTC, and TSCU SFR areas.
3. The blank areas are reserved. No access is allowed.

Part Number	Internal ROM			Internal RAM	
	Capacity	Address 0YYYYh	Address ZZZZZh	Capacity	Address 0XXXXh
R5F21368SNFP/FA, R5F21368SDFP/FA	64 Kbytes	08000h	17FFFh	6 Kbytes	01BFFh
R5F21368SNFP/FA, R5F21368SDFP/FA	96 Kbytes	08000h	1FFFFh	8 Kbytes	023FFh
R5F21368SNFP/FA, R5F21368SDFP/FA	128 Kbytes	08000h	27FFFh	10 Kbytes	02BFFh

Figure 3.1 Memory Map

Table 3.7 SFR Information (7) (1)

Address	Symbol	Register Name	After Reset	Remarks
0017Ah	TREIFR	Timer RE2 Interrupt Flag Register	00h	
0017Bh	TREIER	Timer RE2 Interrupt Enable Register	00h	
0017Ch	TREAMN	Timer RE2 Alarm Minute Register	00h	
0017Dh	TREAHR	Timer RE2 Alarm Hour Register	00h	
0017Eh	TREAWK	Timer RE2 Alarm Day-of-the-Week Register	00h	
0017Fh	TREPRC	Timer RE2 Protect Register	00h	
00180h to 001FFh				
00200h	AD0	A/D Register 0	00h	
00201h			00h	
00202h	AD1	A/D Register 1	00h	
00203h			00h	
00204h	AD2	A/D Register 2	00h	
00205h			00h	
00206h	AD3	A/D Register 3	00h	
00207h			00h	
00208h	AD4	A/D Register 4	00h	
00209h			00h	
0020Ah	AD5	A/D Register 5	00h	
0020Bh			00h	
0020Ch	AD6	A/D Register 6	00h	
0020Dh			00h	
0020Eh	AD7	A/D Register 7	00h	
0020Fh			00h	
00210h				
00211h				
00212h				
00213h				
00214h	ADMOD	A/D Mode Register	00h	
00215h	ADINSEL	A/D Input Select Register	11000000b	
00216h	ADCON0	A/D Control Register 0	00h	
00217h	ADCON1	A/D Control Register 1	00h	
00218h				
00219h				
0021Ah				
0021Bh				
0021Ch				
0021Dh				
0021Eh				
0021Fh				
00220h				
00221h				
00222h				
00223h				
00224h				
00225h				
00226h				
00227h				
00228h	INTCMP	Comparator B Control Register 0	00h	
00229h				
0022Ah				
0022Bh				
0022Ch				
0022Dh				
0022Eh				
0022Fh				
00230h	INTEN	External Input Enable Register 0	00h	
00231h	INTEN1	External Input Enable Register 1	00h	
00232h	INTF	INT Input Filter Select Register 0	00h	
00233h	INTF1	INT Input Filter Select Register 1	00h	
00234h	INTPOL	INT Input Polarity Switch Register	00h	
00235h				
00236h	KIEN	Key Input Interrupt Enable Register	00h	
00237h				
00238h	MSTCR0	Module Standby Control Register 0	00h	
00239h	MSTCR1	Module Standby Control Register 1	00h	

Note:
1. The blank areas are reserved. No access is allowed.

Table 3.8 SFR Information (8) (1)

Address	Symbol	Register Name	After Reset	Remarks
0023Ah	MSTCR2	Module Standby Control Register 2	00h	
0023Bh	MSTCR3	Module Standby Control Register 3	00h	
0023Ch	MSTCR4	Module Standby Control Register 4	00h	
0023Dh				
0023Eh				
0023Fh				
00240h				
00241h				
00242h				
00243h				
00244h				
00245h				
00246h				
00247h				
00248h				
00249h				
0024Ah				
0024Bh				
0024Ch				
0024Dh				
0024Eh				
0024Fh				
00250h				
00251h				
00252h	FST	Flash Memory Status Register	10000X00b	
00253h				
00254h	FMR0	Flash Memory Control Register 0	00h	
00255h	FMR1	Flash Memory Control Register 1	00h	
00256h	FMR2	Flash Memory Control Register 2	00h	
00257h				
00258h				
00259h				
0025Ah				
0025Bh				
0025Ch				
0025Dh				
0025Eh				
0025Fh				
00260h	AIADR0L	Address Match Interrupt Address 0L Register	XXXXh	
00261h				
00262h	AIADR0H	Address Match Interrupt Address 0H Register	0000XXXXb	
00263h	AIEN0	Address Match Interrupt Enable 0 Register	00h	
00264h	AIADR1L	Address Match Interrupt Address 1L Register	XXXXh	
00265h				
00266h	AIADR1H	Address Match Interrupt Address 1H Register	0000XXXXb	
00267h	AIEN1	Address Match Interrupt Enable 1 Register	00h	
00268h				
00269h				
0026Ah				
0026Bh				
0026Ch				
0026Dh				
0026Eh				
0026Fh				
00270h				
00271h				
00272h				
00273h				
00274h				
00275h				
00276h				
00277h				
00278h				
00279h				
0027Ah				
0027Bh				
0027Ch				
0027Dh				
0027Eh				
0027Fh				

X: Undefined

Note:

1. The blank areas are reserved. No access is allowed.

Table 3.14 SFR Information (14) (1)

Address	Symbol	Register Name	After Reset	Remarks
06C4Ah	DTCCT1	DTC Transfer Count Register 1	XXh	
06C4Bh	DTRLD1	DTC Transfer Count Reload Register 1	XXh	
06C4Ch	DTSAR1	DTC Source Address Register 1	XXXXh	
06C4Dh				
06C4Eh	DTDAR1	DTC Destination Address Register 1	XXXXh	
06C4Fh				
06C50h	DTCCR2	DTC Control Register 2	XXh	
06C51h	DTBLS2	DTC Block Size Register 2	XXh	
06C52h	DTCCT2	DTC Transfer Count Register 2	XXh	
06C53h	DTRLD2	DTC Transfer Count Reload Register 2	XXh	
06C54h	DTSAR2	DTC Source Address Register 2	XXXXh	
06C55h				
06C56h	DTDAR2	DTC Destination Address Register 2	XXXXh	
06C57h				
06C58h	DTCCR3	DTC Control Register 3	XXh	
06C59h	DTBLS3	DTC Block Size Register 3	XXh	
06C5Ah	DTCCT3	DTC Transfer Count Register 3	XXh	
06C5Bh	DTRLD3	DTC Transfer Count Reload Register 3	XXh	
06C5Ch	DTSAR3	DTC Source Address Register 3	XXXXh	
06C5Dh				
06C5Eh	DTDAR3	DTC Destination Address Register 3	XXXXh	
06C5Fh				
06C60h	DTCCR4	DTC Control Register 4	XXh	
06C61h	DTBLS4	DTC Block Size Register 4	XXh	
06C62h	DTCCT4	DTC Transfer Count Register 4	XXh	
06C63h	DTRLD4	DTC Transfer Count Reload Register 4	XXh	
06C64h	DTSAR4	DTC Source Address Register 4	XXXXh	
06C65h				
06C66h	DTDAR4	DTC Destination Address Register 4	XXXXh	
06C67h				
06C68h	DTCCR5	DTC Control Register 5	XXh	
06C69h	DTBLS5	DTC Block Size Register 5	XXh	
06C6Ah	DTCCT5	DTC Transfer Count Register 5	XXh	
06C6Bh	DTRLD5	DTC Transfer Count Reload Register 5	XXh	
06C6Ch	DTSAR5	DTC Source Address Register 5	XXXXh	
06C6Dh				
06C6Eh	DTDAR5	DTC Destination Address Register 5	XXXXh	
06C6Fh				
06C70h	DTCCR6	DTC Control Register 6	XXh	
06C71h	DTBLS6	DTC Block Size Register 6	XXh	
06C72h	DTCCT6	DTC Transfer Count Register 6	XXh	
06C73h	DTRLD6	DTC Transfer Count Reload Register 6	XXh	
06C74h	DTSAR6	DTC Source Address Register 6	XXXXh	
06C75h				
06C76h	DTDAR6	DTC Destination Address Register 6	XXXXh	
06C77h				
06C78h	DTCCR7	DTC Control Register 7	XXh	
06C79h	DTBLS7	DTC Block Size Register 7	XXh	
06C7Ah	DTCCT7	DTC Transfer Count Register 7	XXh	
06C7Bh	DTRLD7	DTC Transfer Count Reload Register 7	XXh	
06C7Ch	DTSAR7	DTC Source Address Register 7	XXXXh	
06C7Dh				
06C7Eh	DTDAR7	DTC Destination Address Register 7	XXXXh	
06C7Fh				
06C80h	DTCCR8	DTC Control Register 8	XXh	
06C81h	DTBLS8	DTC Block Size Register 8	XXh	
06C82h	DTCCT8	DTC Transfer Count Register 8	XXh	
06C83h	DTRLD8	DTC Transfer Count Reload Register 8	XXh	
06C84h	DTSAR8	DTC Source Address Register 8	XXXXh	
06C85h				
06C86h	DTDAR8	DTC Destination Address Register 8	XXXXh	
06C87h				
06C88h	DTCCR9	DTC Control Register 9	XXh	
06C89h	DTBLS9	DTC Block Size Register 9	XXh	
06C8Ah	DTCCT9	DTC Transfer Count Register 9	XXh	
06C8Bh	DTRLD9	DTC Transfer Count Reload Register 9	XXh	
06C8Ch	DTSAR9	DTC Source Address Register 9	XXXXh	
06C8Dh				
06C8Eh	DTDAR9	DTC Destination Address Register 9	XXXXh	
06C8Fh				

X: Undefined

Note:

1. The blank areas are reserved. No access is allowed.

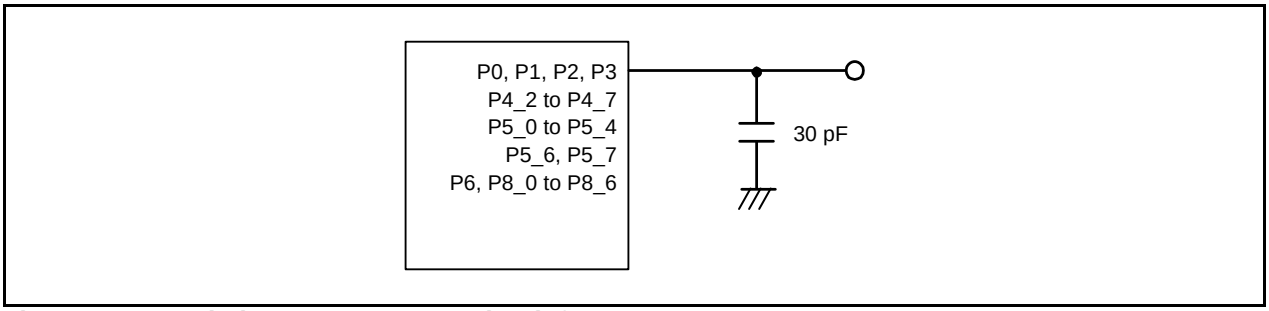


Figure 4.1 Timing Measurement Circuit for Ports P0, P1, P2, P3, P4_2 to P4_7, P5_0 to P5_4, P5_6, P5_7, P6, and P8_0 to P8_6

Table 4.6 Flash Memory (Data flash Block A to Block D) Characteristics (Vcc = 2.7 V to 5.5 V, Topr = –20°C to 85°C (N version)/–40°C to 85°C (D version), unless otherwise specified)

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
—	Program/erase endurance (1)		10,000 (2)	—	—	times
—	Byte program time (Program and erase endurance ≤ 1,000 times)		—	160	950	µs
—	Byte program time (Program and erase endurance > 1,000 times)		—	300	950	µs
—	Block erase time (Program and erase endurance ≤ 1,000 times)		—	0.2	1	s
—	Block erase time (Program and erase endurance > 1,000 times)		—	0.3	1	s
$t_{d(SR-SUS)}$	Time delay from suspend request until suspend		—	—	3 + CPU clock × 3 cycles	ms
—	Interval from erase start/restart until following suspend request		0	—	—	µs
—	Time from suspend until erase restart		—	—	30 + CPU clock × 1 cycle	µs
$t_{d(CMDRST-READY)}$	Time from when command is forcibly terminated until reading is enabled		—	—	30 + CPU clock × 1 cycle	µs
—	Program, erase voltage		2.7	—	5.5	V
—	Read voltage		1.8	—	5.5	V
—	Program, erase temperature		–20 (N ver.) –40 (D ver.)	—	85	°C
—	Data hold time (6)	Ambient temperature = 55°C (7)	20	—	—	year

Notes:
1. Definition of programming/erasure endurance
   The programming and erasure endurance is defined on a per-block basis.
   If the programming and erasure endurance is n (n = 100, 1,000 or 10,000), each block can be erased n times. For example, if 1,024 1-byte writes are performed to different addresses in block A, a 1 Kbyte block, and then the block is erased, the programming/erasure endurance still stands at one.
   However, the same address must not be programmed more than once per erase operation (overwriting prohibited).
2. Endurance to guarantee all electrical characteristics after program and erase. (1 to Min. value can be guaranteed).
3. In a system that executes multiple programming operations, the actual erasure count can be reduced by writing to sequential addresses in turn so that as much of the block as possible is used up before performing an erase operation. For example, when programming groups of 16 bytes, the effective number of rewrites can be minimized by programming up to 128 groups before erasing them all in one operation. In addition, averaging the erasure endurance between blocks A to D can further reduce the actual erasure endurance. It is also advisable to retain data on the erasure endurance of each block and limit the number of erase operations to a certain number.
4. If an error occurs during block erase, attempt to execute the clear status register command, then execute the block erase command at least three times until the erase error does not occur.
5. Customers desiring program/erase failure rate information should contact their Renesas technical support representative.
6. The data hold time includes time that the power supply is off or the clock is not supplied.
7. The data hold time includes 7,000 hours under an environment of ambient temperature 85°C.

Table 4.8 Voltage Detection 1 Circuit Characteristics (Measurement conditions: Vcc = 1.8 V to 5.5 V, Topr = –20°C to 85°C (N version)/ –40°C to 85°C (D version))

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
V_{det1}	Voltage detection level Vdet1_0 (1)	When Vcc falls	2.00	2.20	2.40	V
	Voltage detection level Vdet1_1 (1)	When Vcc falls	2.15	2.35	2.55	V
	Voltage detection level Vdet1_2 (1)	When Vcc falls	2.30	2.50	2.70	V
	Voltage detection level Vdet1_3 (1)	When Vcc falls	2.45	2.65	2.85	V
	Voltage detection level Vdet1_4 (1)	When Vcc falls	2.60	2.80	3.00	V
	Voltage detection level Vdet1_5 (1)	When Vcc falls	2.75	2.95	3.15	V
	Voltage detection level Vdet1_6 (1)	When Vcc falls	2.80	3.10	3.40	V
	Voltage detection level Vdet1_7 (1)	When Vcc falls	2.95	3.25	3.55	V
	Voltage detection level Vdet1_8 (1)	When Vcc falls	3.10	3.40	3.70	V
	Voltage detection level Vdet1_9 (1)	When Vcc falls	3.25	3.55	3.85	V
	Voltage detection level Vdet1_A (1)	When Vcc falls	3.40	3.70	4.00	V
	Voltage detection level Vdet1_B (1)	When Vcc falls	3.55	3.85	4.15	V
	Voltage detection level Vdet1_C (1)	When Vcc falls	3.70	4.00	4.30	V
	Voltage detection level Vdet1_D (1)	When Vcc falls	3.85	4.15	4.45	V
	Voltage detection level Vdet1_E (1)	When Vcc falls	4.00	4.30	4.60	V
	Voltage detection level Vdet1_F (1)	When Vcc falls	4.15	4.45	4.75	V
—	Hysteresis width at the rising of Vcc in voltage detection 1 circuit	Vdet1_0 to Vdet1_5 selected	—	0.07	—	V
		Vdet1_6 to Vdet1_F selected	—	0.10	—	V
—	Voltage detection 1 circuit response time (2)	At the falling of Vcc from 5 V to (Vdet1 – 0.1) V	—	60	150	µs
—	Voltage detection circuit self power consumption	VCA26 = 1, Vcc = 5.0 V	—	1.7	—	µA
$t_{d(E-A)}$	Waiting time until voltage detection circuit operation starts (3)		—	—	100	µs

Notes:
1. Select the voltage detection level with bits VD1S0 to VD1S3 in the VD1LS register.
2. Time until the voltage monitor 1 interrupt request is generated after the voltage passes V_{det1}.
3. Necessary time until the voltage detection circuit operates when setting to 1 again after setting the VCA26 bit in the VCA2 register to 0.

Table 4.9 Voltage Detection 2 Circuit Characteristics (Measurement conditions: Vcc = 1.8 V to 5.5 V, Topr = –20°C to 85°C (N version)/ –40°C to 85°C (D version))

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
V_{det2}	Voltage detection level Vdet2_0	When Vcc falls	3.70	4.00	4.30	V
—	Hysteresis width at the rising of Vcc in voltage detection 2 circuit		—	0.1	—	µs
—	Voltage detection 2 circuit response time (1)	At the falling of Vcc from 5 V to (Vdet2_0 – 0.1) V	—	20	150	µs
—	Voltage detection circuit self power consumption	VCA27 = 1, Vcc = 5.0 V	—	1.7	—	µA
$t_{d(E-A)}$	Waiting time until voltage detection circuit operation starts (2)		—	—	100	µs

Notes:
1. Time until the voltage monitor 2 interrupt request is generated after the voltage passes V_{det2}.
2. Necessary time until the voltage detection circuit operates when setting to 1 again after setting the VCA26 bit in the VCA2 register to 0.

4.4 DC Characteristics

Table 4.14 DC Characteristics (1) [4.2 V ≤ Vcc ≤ 5.5 V] (Measurement conditions: Vcc = 1.8 V to 5.5 V, Topr = –20°C to 85°C (N version)/ –40°C to 85°C (D version))

Symbol	Parameter		Conditions		Standard			Unit
					Min.	Typ.	Max.	
V_{OH}	Output high voltage	Other than XOUT	Drive capacity is high	I_{OH} = –20 mA	Vcc – 2.0	—	Vcc	V
			Drive capacity is low	I_{OH} = –5 mA	Vcc – 2.0	—	Vcc	V
				I_{OH} = –200 µA	Vcc – 0.3	—	Vcc	V
		XOUT		I_{OH} = –200 µA	1.0	—	Vcc	V
V_{OL}	Output low voltage	Other than XOUT	Drive capacity is high	I_{OL}= 20 mA	—	—	2.0	V
			Drive capacity is low	I_{OL} = 5 mA	—	—	2.0	V
				I_{OL} = 200 µA	—	—	0.45	V
		XOUT		I_{OL} = 200 µA	—	—	0.5	V
V_{T+}-V_{T-}	Hysteresis	$\overline{INT0}$ to $\overline{INT4}$, $\overline{KI0}$ to $\overline{KI3}$, TRJIO_0, TRCCLK_0, TRCTRG_0, TRCIOA_0, TRCIOB_0, TRCIOC_0, TRCIOD_0, CLK_0, CLK_1, $\overline{RXD\_0}$, RXD_1, $\overline{CTS2}$, SCL2, SDA2, CLK2, RXD2, $\underline{SCL\_0}$, SDA_0, SSI_0, $\overline{SCS\_0}$, SSCK_0, SSO_0			0.1	1.2	—	V
		$\overline{RESET}$	Vcc = 5.0 V		0.1	1.2	—	V
I_{IH}	Input high current		V_I = 5.0 V		—	—	1.0	µA
I_{IL}	Input low current		V_I = 0 V		—	—	–1.0	µA
R_{PULLUP}	Pull-up resistance		V_I = 0 V		25	50	100	kΩ
R_{fXIN}	Feedback resistance	XIN			—	0.3	—	MΩ
R_{fXCIN}	Feedback resistance	XCIN			—	8	—	MΩ
V_{RAM}	RAM hold voltage		During stop mode		1.8	—	—	V

Table 4.16 DC Characteristics (3) [2.7 V ≤ Vcc < 4.2 V]
(Measurement conditions: Vcc = 1.8 V to 5.5 V, Topr = –20°C to 85°C (N version)/ –40°C to 85°C (D version))

Symbol	Parameter		Conditions		Standard			Unit
					Min.	Typ.	Max.	
V_{OH}	Output high voltage	Other than XOUT	Drive capacity is high	I_{OH} = –5 mA	Vcc – 0.5	—	Vcc	V
			Drive capacity is low	I_{OH} = –1 mA	Vcc – 0.5	—	Vcc	V
		XOUT		I_{OH} = –200 µA	1.0	—	Vcc	V
V_{OL}	Output low voltage	Other than XOUT	Drive capacity is high	I_{OL} = 5 mA	—	—	0.5	V
			Drive capacity is low	I_{OL} = 1 mA	—	—	0.5	V
		XOUT		I_{OL} = 200 µA	—	—	0.5	V
V_{T+}-V_{T-}	Hysteresis	$\overline{INT0}$ to $\overline{INT4}$, $\overline{KI0}$ to $\overline{KI3}$, TRJIO_0, TRCCLK_0, TRCTRG_0, TRCIOA_0, TRCIOB_0, TRCIOC_0, TRCIOD_0, CLK_0, CLK_1, RXD_0, RXD_1, $\overline{CTS2}$, SCL2, SDA2, CLK2, RXD2, $\underline{SCL\_0}$, SDA_0, SSI_0, $\overline{SCS\_0}$, SSCK_0, SSO_0			0.1	0.4	—	V
		$\overline{RESET}$	Vcc = 3.0 V		0.1	0.5	—	V
I_{IH}	Input high current		V_I = 3.0 V		—	—	1.0	µA
I_{IL}	Input low current		V_I = 0 V		—	—	–1.0	µA
R_{PULLUP}	Pull-up resistance		V_I = 0 V		42	84	168	kΩ
R_{fXIN}	Feedback resistance	XIN			—	0.3	—	MΩ
R_{fXCIN}	Feedback resistance	XCIN			—	8	—	MΩ
V_{RAM}	RAM hold voltage		During stop mode		1.8	—	—	V

Table 4.19 DC Characteristics (6) [1.8 V ≤ Vcc < 2.7 V] (Topr = –20°C to 85°C (N version)/–40°C to 85°C (D version), unless otherwise specified)

Symbol	Parameter	Conditions								Standard (4)			Unit
			Oscillation		On-Chip Oscillator		CPU Clock	Low-Power-Consumption Setting	Other	Min.	Typ.	Max.	
			XIN (2)	XCIN	High-Speed	Low-Speed							
Icc	Power supply current (1)	High-speed clock mode	5 MHz	Off	Off	125 kHz	No division	—		—	2.2	—	mA
			5 MHz	Off	Off	125 kHz	Divide-by-8	—		—	0.8	—	mA
		High-speed on-chip oscillator mode	Off	Off	5 MHz (3)	125 kHz	No division	—		—	2.5	10	mA
			Off	Off	5 MHz (3)	125 kHz	Divide-by-8	—		—	1.7	—	mA
			Off	Off	4 MHz (3)	125 kHz	Divide-by-16	MSTIIC = 1 MSTTRC = 1		—	1	—	mA
		Low-speed on-chip oscillator mode	Off	Off	Off	125 kHz	Divide-by-8	FMR27 = 1 SVC0 = 0		—	90	300	µA
		Low-speed clock mode	Off	32 kHz	Off	Off	No division	FMR27 = 1 SVC0 = 0		—	80	350	µA
		Wait mode	Off	Off	Off	125 kHz	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 SVC0 = 1	While a WAIT instruction is executed Peripheral clock operation	—	15	90	µA
			Off	Off	Off	125 kHz	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 SVC0 = 1	While a WAIT instruction is executed Peripheral clock off	—	4	80	µA
			Off	32 kHz	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 SVC0 = 1	While a WAIT instruction is executed Peripheral clock off	—	3.5	—	µA
		Stop mode	Off	Off	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Topr = 25°C Peripheral clock off	—	2.2	6	µA
			Off	Off	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Topr = 85°C Peripheral clock off	—	30	—	µA

Notes:
1. Vcc = 1.8 V to 2.7 V, single-chip mode, output pins are open, and other pins are Vss.
2. XIN is set to square wave input.
3. fHOCO-F
4. The typical value (Typ.) indicates the current value when the CPU and the memory operate.
   The maximum value (Max.) indicates the current value when the CPU, the memory, and the peripheral functions operate and the flash memory is programmed/erased.

4.5 AC Characteristics

Table 4.20 Timing Requirements of Clock Synchronous Serial I/O with Chip Select (during Master Operation) (Measurement conditions: Vcc = 1.8 V to 5.5 V, Topr = –20°C to 85°C (N version)/ –40°C to 85°C (D version))

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
t_{SUCYC}	SSCK clock cycle time		4.00	—	—	t_{CYC} (1)
t_{HI}	SSCK clock high width		0.40	—	0.60	t_{SUCYC}
t_{LO}	SSCK clock low width		0.40	—	0.60	t_{SUCYC}
t_{RISE}	SSCK clock rising time	2.7 V ≤ Vcc ≤ 5.5 V	—	—	0.50	t_{CYC} (1)
		1.8 V ≤ Vcc < 2.7 V	—	—	1.00	t_{CYC} (1)
t_{FALL}	SSCK clock falling time	2.7 V ≤ Vcc ≤ 5.5 V	—	—	0.50	t_{CYC} (1)
		1.8 V ≤ Vcc < 2.7 V	—	—	1.00	t_{CYC} (1)
t_{SU}	SSI, SSO data input setup time	4.5 V ≤ Vcc ≤ 5.5 V	60	—	—	ns
		2.7 V ≤ Vcc < 4.5 V	70	—	—	ns
		1.8 V ≤ Vcc < 2.7 V	100	—	—	ns
t_H	SSI, SSO data input hold time	2.7 V ≤ Vcc ≤ 5.5 V	2.00	—	—	t_{CYC} (1)
		1.8 V ≤ Vcc < 2.7 V	2.00	—	—	t_{CYC} (1)
t_{LEAD}	$\overline{SCS}$-SCK output delay time		0.5 t_{SUCYC} - 1 t_{CYC}	—	—	ns
t_{LAG}	SCK -$\overline{SCS}$ output valid time		0.5 t_{SUCYC} - 1 t_{CYC}	—	—	ns
t_{OD}	SSO data output delay time	2.7 V ≤ Vcc ≤ 5.5 V	—	—	30.00	ns
		1.8 V ≤ Vcc < 2.7 V	—	—	1.00	t_{CYC} (1)

Note:
1. $1t_{CYC} = 1/f1$ (s)

Table 4.26 Timing Requirements of External Interrupt $\overline{INTi}$ (i = 0 to 4) and Key Input Interrupt $\overline{KIj}$ (j = 0 to 3)

Symbol	Parameter	Standard						Unit
		Vcc = 2.2 V, Topr = 25°C		Vcc = 3 V, Topr = 25°C		Vcc = 5 V, Topr = 25°C		
		Min.	Max.	Min.	Max.	Min.	Max.	
$t_{W(INH)}$	$\overline{INTi}$ input high width, $\overline{KIj}$ input high width	1000 (1)	—	380 (1)	—	250 (1)	—	ns
$t_{W(INL)}$	$\overline{INTi}$ input low width, $\overline{KIj}$ input low width	1000 (2)	—	380 (2)	—	250 (2)	—	ns

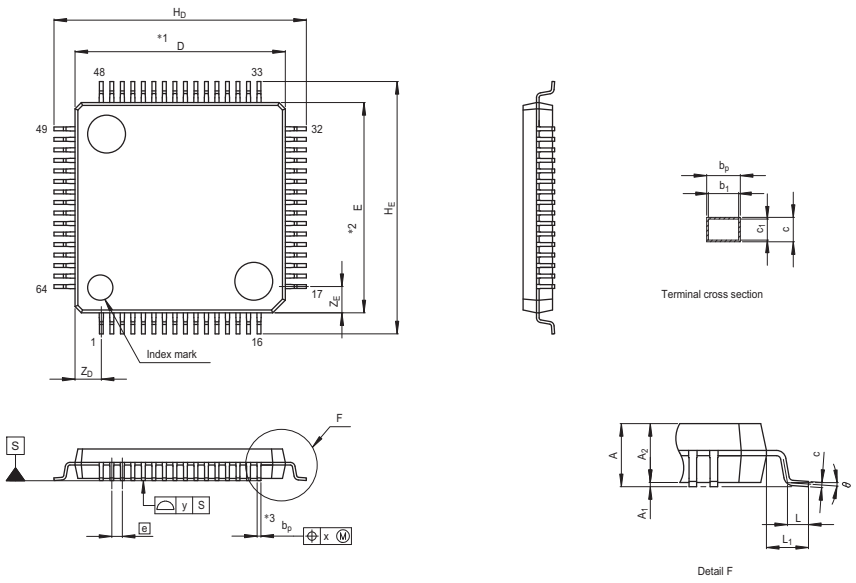
Notes:
1. When selecting the digital filter by the $\overline{INTi}$ input filter select bit, use an $\overline{INTi}$ input high pulse width of either (1/digital filter sampling frequency × 3) or the minimum value of standard, whichever is greater.
2. When selecting the digital filter by the $\overline{INTi}$ input filter select bit, use an $\overline{INTi}$ input low pulse width of either (1/digital filter sampling frequency × 3) or the minimum value of standard, whichever is greater.

Figure 4.10 Input Timing of External Interrupt $\overline{INTi}$ and Key Input Interrupt $\overline{KIj}$ (i = 0 to 4; j = 0 to 3)

Appendix 1. Package Dimensions

Diagrams showing the latest package dimensions and mounting information are available in the “Packages” section of the Renesas Electronics website.

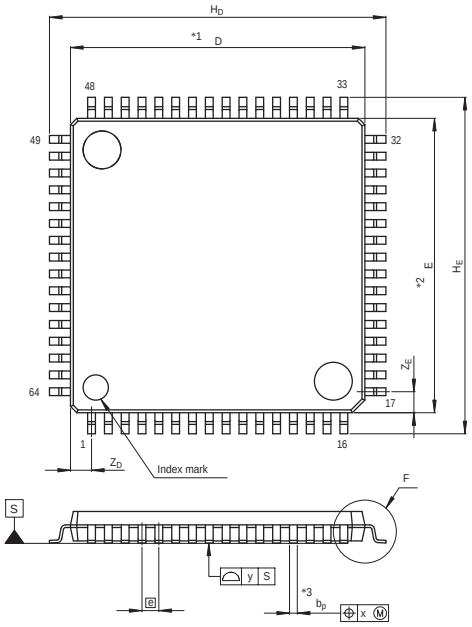
JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-LQFP64-10x10-0.50	PLQP0064KB-A	64P6Q-A / FP-64K / FP-64KV	0.3g

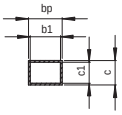


NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION "*3" DOES NOT INCLUDE TRIM OFFSET.

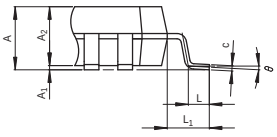
Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	9.9	10.0	10.1
E	9.9	10.0	10.1
A_2	—	1.4	—
H_D	11.8	12.0	12.2
H_E	11.8	12.0	12.2
A	—	—	1.7
A_1	0.05	0.1	0.15
b_p	0.15	0.20	0.25
b_1	—	0.18	—
c	0.09	0.145	0.20
c_1	—	0.125	—
θ	0°	—	8°
e	—	0.5	—
x	—	—	0.08
y	—	—	0.08
Z_D	—	1.25	—
Z_E	—	1.25	—
L	0.35	0.5	0.65
L_1	—	1.0	—

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-LQFP64-14x14-0.80	PLQP0064GA-A	64P6U-A/ —	0.7g





Terminal cross section



Detail F

NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION "*3" DOES NOT INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	13.9	14.0	14.1
E	13.9	14.0	14.1
A_2	—	1.4	—
H_D	15.8	16.0	16.2
H_E	15.8	16.0	16.2
A	—	—	1.7
A_1	0	0.1	0.2
b_p	0.32	0.37	0.42
b_1	—	0.35	—
c	0.09	0.145	0.20
c_1	—	0.125	—
θ	0°	—	8°
e	—	0.8	—
x	—	—	0.20
y	—	—	0.10
Z_D	—	1.0	—
Z_E	—	1.0	—
L	0.3	0.5	0.7
L_1	—	1.0	—

REVISION HISTORY	R8C/36T-A Group Datasheet

Rev.	Date	Description	
		Page	Summary
0.01	Feb 23, 2011	—	First Edition issued
1.00	Dec 09, 2011	All pages	“Preliminary”, “Under development” deleted, “sensor control unit” → “touch sensor control unit”
		2, 3	Tables 1.1 and 1.2 revised
		6	Figure 1.3 “P3_10/CH10” → “P3_1/CH10”
		11	Table 1.8 “Touch sensor control unit” added
		13	2.1 revised
		16, 17, 19 to 22, 24 to 28	Tables 3.1, 3.2, 3.4 to 3.7, 3.9 to 3.13
		32	Table 3.17 revised, Note 2 added
		33 to 56	“4. Electrical Characteristics” added

General Precautions in the Handling of MPU/MCU Products

The following usage notes are applicable to all MPU/MCU products from Renesas. For detailed usage notes on the products covered by this manual, refer to the relevant sections of the manual. If the descriptions under General Precautions in the Handling of MPU/MCU Products and in the body of the manual differ from each other, the description in the body of the manual takes precedence.

1. Handling of Unused Pins

   Handle unused pins in accord with the directions given under Handling of Unused Pins in the manual.

   — The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible. Unused pins should be handled as described under Handling of Unused Pins in the manual.

2. Processing at Power-on

   The state of the product is undefined at the moment when power is supplied.

   — The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the moment when power is supplied.

   In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the moment when power is supplied until the reset process is completed.

   In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the moment when power is supplied until the power reaches the level at which resetting has been specified.

3. Prohibition of Access to Reserved Addresses

   Access to reserved addresses is prohibited.

   — The reserved addresses are provided for the possible future expansion of functions. Do not access these addresses; the correct operation of LSI is not guaranteed if they are accessed.

4. Clock Signals

   After applying a reset, only release the reset line after the operating clock signal has become stable. When switching the clock signal during program execution, wait until the target clock signal has stabilized.

   — When the clock signal is generated with an external resonator (or from an external oscillator) during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Moreover, when switching to a clock signal produced with an external resonator (or by an external oscillator) while program execution is in progress, wait until the target clock signal is stable.

5. Differences between Products

   Before changing from one product to another, i.e. to one with a different part number, confirm that the change will not lead to problems.

   — The characteristics of MPU/MCU in the same group but having different part numbers may differ because of the differences in internal memory capacity and layout pattern. When changing to products of different part numbers, implement a system-evaluation test for each of the products.